DOCUMENT CHANGE REQUEST

DCR number 1159

Changes required for: General

Originator: Philippe Fellon

Date: 2018/07/13

Date sent: 2018/04/27

Organisation: United Monolithic Semiconductors

Status: IMPLEMENTED

Title:	Monolithic Microwave Integrated Circuit (MMIC) InGaP HBT HB20M Process from UMS, Voltage		
Number:	9012/003	Issue:	2

Other documents affected:

9012/004-1

Page:

Paragraph:

Original wording:

Proposed wording:

Justification:

manufacturers initiated change

Attachments:

9012004_detail_spec_chv1206_iss2_update.docx, 9012003_detail_spec_chv1203_iss2_update.docx, eppl_change_form_chv1203.docx, eppl_change_form_chv1206.docx

Modifications:

Agreed with additional modifications on page 9 for both detailed specifications

Justification:

Changes in size of MMIC are OK (UMS reduced the size of the dice to be compatible with hermetic package, no impact on performances or reliability).
However the size for the DC and RF pads are not correct. The good values are :
RF pad = 105 x 136µm² (BCB opening)
DC pads = 136 x 83µm² (BCB opening)
The attached new detail spec (with the right pad dimensions) have been updated by UMS

Approval signature:
Date signed:
2018-07-13